

Zener Diode DZ2S068C0L

DZ2S068C0L Silicon epitaxial planar type

For ESD protection Bi-directional type

- Features
- High ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: GH

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

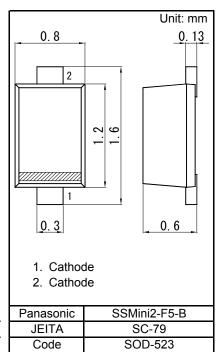
Parameter	Symbol	Rating	Unit	
Total power dissipation ^{*1}	PT	150	mW	
Electrostatic discharge *2	ESD	±15	kV	
Junction temperature	Tj	150	О°	
Operating ambient temperature	Topr	-40 to +85	О°	
Storage temperature	Tstg	-55 to +150	О°	

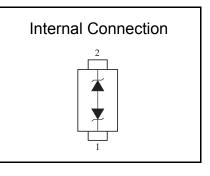
 Storage temperature
 I stg
 -55
 to
 +150

 Note)
 *1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm) Solder in (0.8 mm × 0.6 mm)
 Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)





■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	6.50		7.50	V
Zener operating resistance	RZ	IZ = 5 mA			20	Ω
Reverse current	IR	VR = 4.0 V			50	nA
Terminal capacitance	Ct	VR = 0 V , f = 1MHz		15.0		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. *1 The temperature must be controlled 25 °C for VZ mesurement.

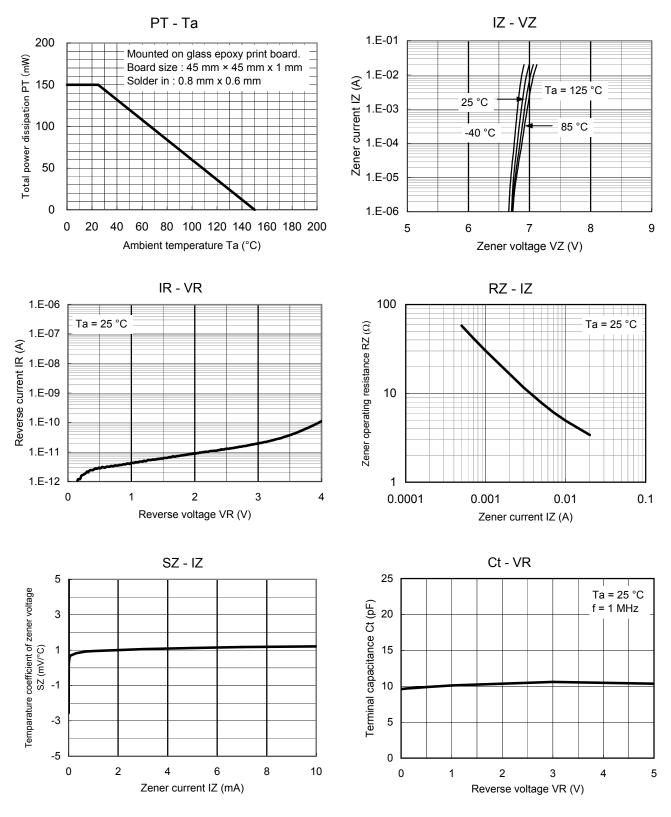
VZ value measured at other temperature must be adjusted to VZ (25 °C).

*2 VZ guaranted 20 ms after current flow



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Technical Data (reference)

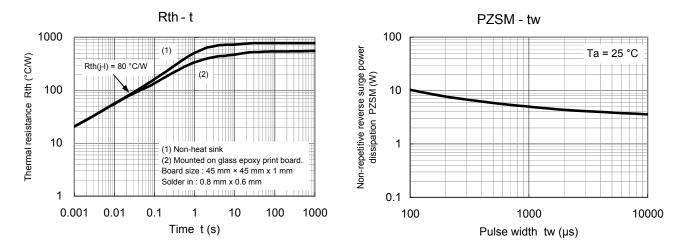


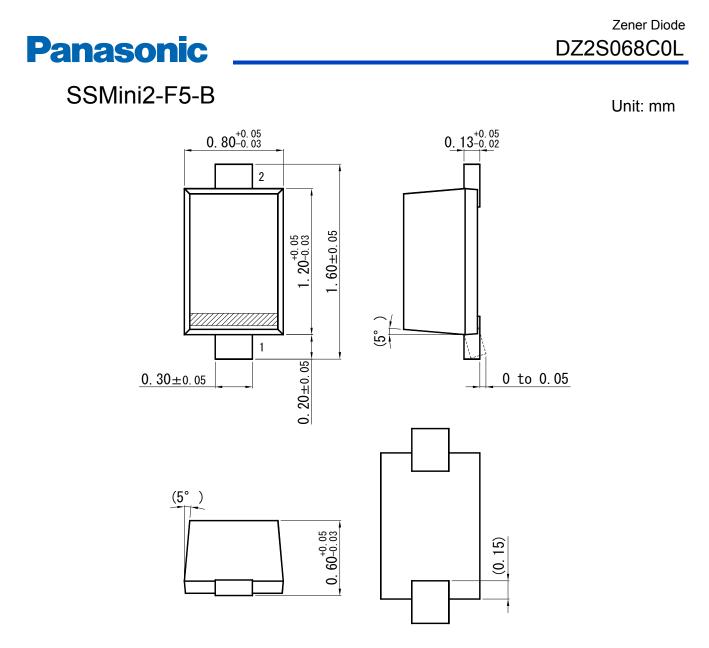
Established : 2009-09-09 Revised : 2013-07-22



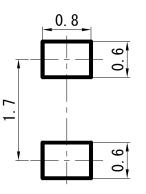
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Technical Data (reference)





Land Pattern (Reference) (Unit: mm)



Established : 2009-09-09 Revised : 2013-07-22

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